



Final Product Change Notification

201607009F01

Issue Date: 09-Aug-2016

Effective Date: 21-Nov-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

Utilize ASEN as a Final Test Location for PCA9511ADP in order to enable full turn-key processing.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Electrical spec./Test coverage

Add ASEN as an additional Final Test Location for PCA9511ADP

Details of this Change

Enable ASEN as an ATE (test) location of the PCA9511ADP to complete turn-key processing.

Why do we Implement this Change

As a JV and strategic partner, ASEN, which is located in Suzhou, China has been supporting the assembly and test of numerous BL SIP products in both assembly only and full turn-key formats. Adding/Implementing the ATE step allows for NXP and the BL to optimize assembly and test capacity by improving flexibility for production planning.

Assembly was previously qualified but enabling ATE-FT step will allow for full turn-key processing.

Identification of Affected Products

Products tested in ASEN are identified via NXP internal traceability. And while the product identification does not change, an improvement is under consideration to provide additional traceability.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 10-Oct-2016

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 08-Sep-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Affected Part Number

PCA9511ADP,118